

Special Issue

MEMS Packaging Technologies and 3D Integration, 2nd Edition

Message from the Guest Editor

MEMS packaging is an essential technique for successful commercialization of MEMS products, as MEMS has moving parts and an application-specific nature. The classic approach of MEMS packaging is to bond silicon or glass cap wafer to MEMS wafers. Therefore, it is typically implemented under high-pressure and high-temperature conditions. Advanced approaches use the thin-film deposition technique, and then the cavity for MEMS is realized by sacrificial etch through access holes at the thin-film cap. The packaging cap transfer technique is a compromise between the two approaches since it makes it possible to bond and transfer the thin packaging cap to the released MEMS device. MEMS devices and IC are being integrated in 3D fashion to achieve better performance, and the implantable device needs special packaging techniques. Thus, this Special Issue seeks research papers, short communications, and review articles that focus on MEMS packaging technologies and related integration methods.

Guest Editor

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Deadline for manuscript submissions

closed (30 November 2023)



Micromachines

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Impact Factor 3.0
CiteScore 5.2
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